

AMENDMENTS TO THE CLAIMS

1. (Currently amended) A method for forming a solder resist pattern comprising the steps of:

pre-treating both sides of a double-sided printed circuit board;

laminating a semi-cured thermosetting film on the both sides of the printed circuit board;

and

irradiating a laser beam to the laminated thermosetting film according to a solder resist mask pattern to selectively remove the thermosetting film, the solder resist mask pattern having been previously designed prior to irradiating, wherein the laser beam is produced by a laser that is used to produce via holes in the printed circuit board.

2. (Original) The method for forming a solder resist pattern according to claim 1, wherein the pretreatment includes scrubbing.

3. (Original) The method for forming a solder resist pattern according to claim 1, further comprising curing the semi-cured thermosetting film after laminating the thermosetting film.

4. (Currently amended) A method for forming a solder resist pattern comprising the steps of:

pretreating a portion exposed from a plurality of layers constituting a multilayer printed circuit board fabricated by buildup process;

laminating a thermosetting film on the pretreated portion; and

irradiating a laser beam to the laminated thermosetting film according to a solder resist mask pattern to selectively remove the thermosetting film, wherein the laser beam is produced by a laser that is used to produce via holes in the printed circuit board.

5. (Original) The method for forming a solder resist pattern according to claim 4, wherein the pretreatment includes scrubbing.

6. (Original) The method for forming a solder resist pattern according to claim 5, further comprising curing the semi-cured thermosetting film after laminating the thermosetting film.

7. (Currently amended) A method for forming a solder resist pattern comprising the steps of:

pretreating a portion exposed from a plurality of layers constituting a multilayer printed circuit board fabricated in a parallel manner;

laminating a thermosetting film on the pretreated portion; and

irradiating a laser beam to the laminated thermosetting film according to a solder resist mask pattern to selectively remove the thermosetting film, wherein the laser beam is produced by a laser that is used to produce via holes in the printed circuit board.

8. (Original) The method for forming a solder resist pattern according to claim 7, wherein the pretreatment includes scrubbing.

9. (Original) The method for forming a solder resist pattern according to claim 8, further comprising curing the semi-cured thermosetting film after laminating the thermosetting film.

10. (New) The method of Claim 1, wherein the laser is a yttrium aluminum garnet laser, excimer laser, or carbon dioxide laser.

11. (New) The method of Claim 4, wherein the laser is a yttrium aluminum garnet laser, excimer laser, or carbon dioxide laser.

12. (New) The method of Claim 7, wherein the laser is a yttrium aluminum garnet laser, excimer laser, or carbon dioxide laser.